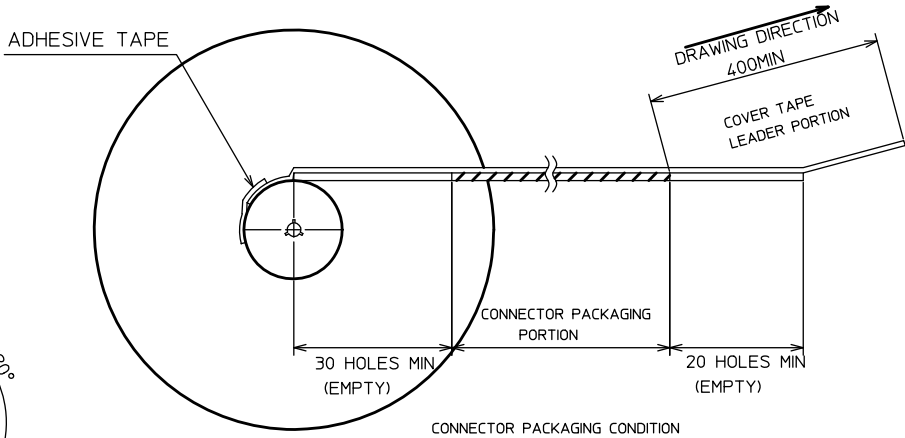
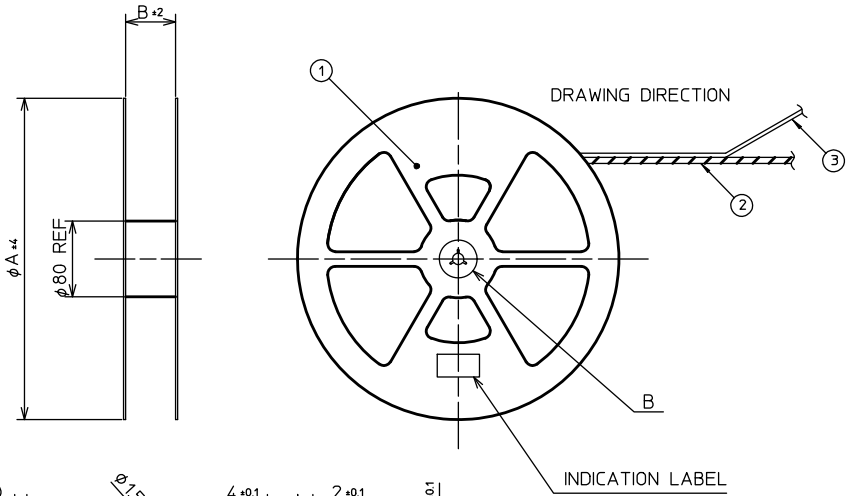


PRODUCT NO
10061122-**-1**0*LF

EMBOSS TAPE	DIMENSIONS		
	φ A	B	C
10061122-131**0*LF~451**0*LF	φ330	25.5	24
10061122-511**0*LF~		33.5	32

PT.NO.	PARTS NAME	PRODUCT NO.	MATERIAL	Q'TY	NOTE
1	REEL		POLYSTYRENE	1	COLOR:WHITE.ELECTRIFICATION PREVENTION PROCESSING
2	EMBOSS TAPE		PP OR PET	1	ELECTRIFICATION PREVENTION PROCESSING
3	COVER TAPE		POLYESTER		
4	CONNECTOR	10061122-**-1**0*LF	10061122 SHEET2,3	5000	
		10061122-**-1**HLF	10061122 SHEET4,5 6,7		



NOTE
1.THIS ARTICLE CARRIES OUT THE EMBOSS TAPE PACKAGE OF THE P/N10061122 SERIES CONNECTOR
2.THE SHAPE AND DIMENSION OF THIS ARTICLE ARE BASED ON JIS C 0806 (TAPING OF ELECTRONIC PARTS(SURFACE MOUNTED DEVICE))

P/N COMPOSITION
10061122-**-1**0*LF

HOUSING MATERIAL 1: NONE-HALOGEN FREE RESIN
2: HALOGEN FREE RESIN

LEAD FREE

PACKAGING FORM (E PLASTIC REEL/EMBOSS TAPE PACKAGE)

EMBOSSING TAPE PACKAGE 0: 8mm PITCH

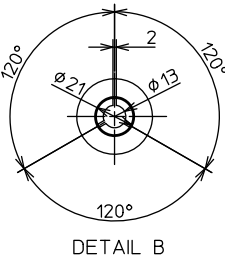
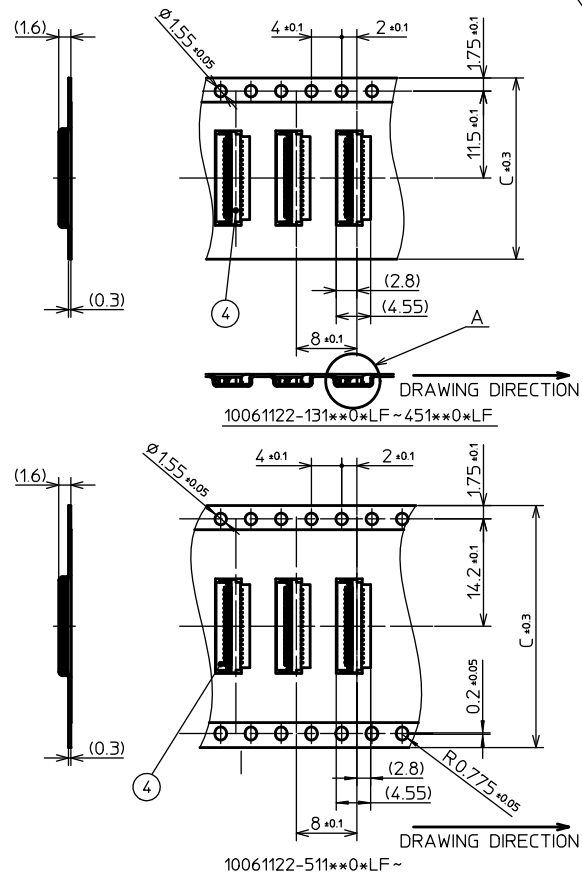
PLATING SPEC 1: AU PLATING

MOUNTING 1: SMT/WITH CABLE LOCK
2: SMT/WITHOUT CABLE LOCK
3: SMT/WITH CABLE LOCK/WITH ACTUATOR LOCK
4: SMT/WITHOUT CABLE LOCK/WITH ACTUATOR LOCK

CONTACT SIDE 1: DOWN SIDE

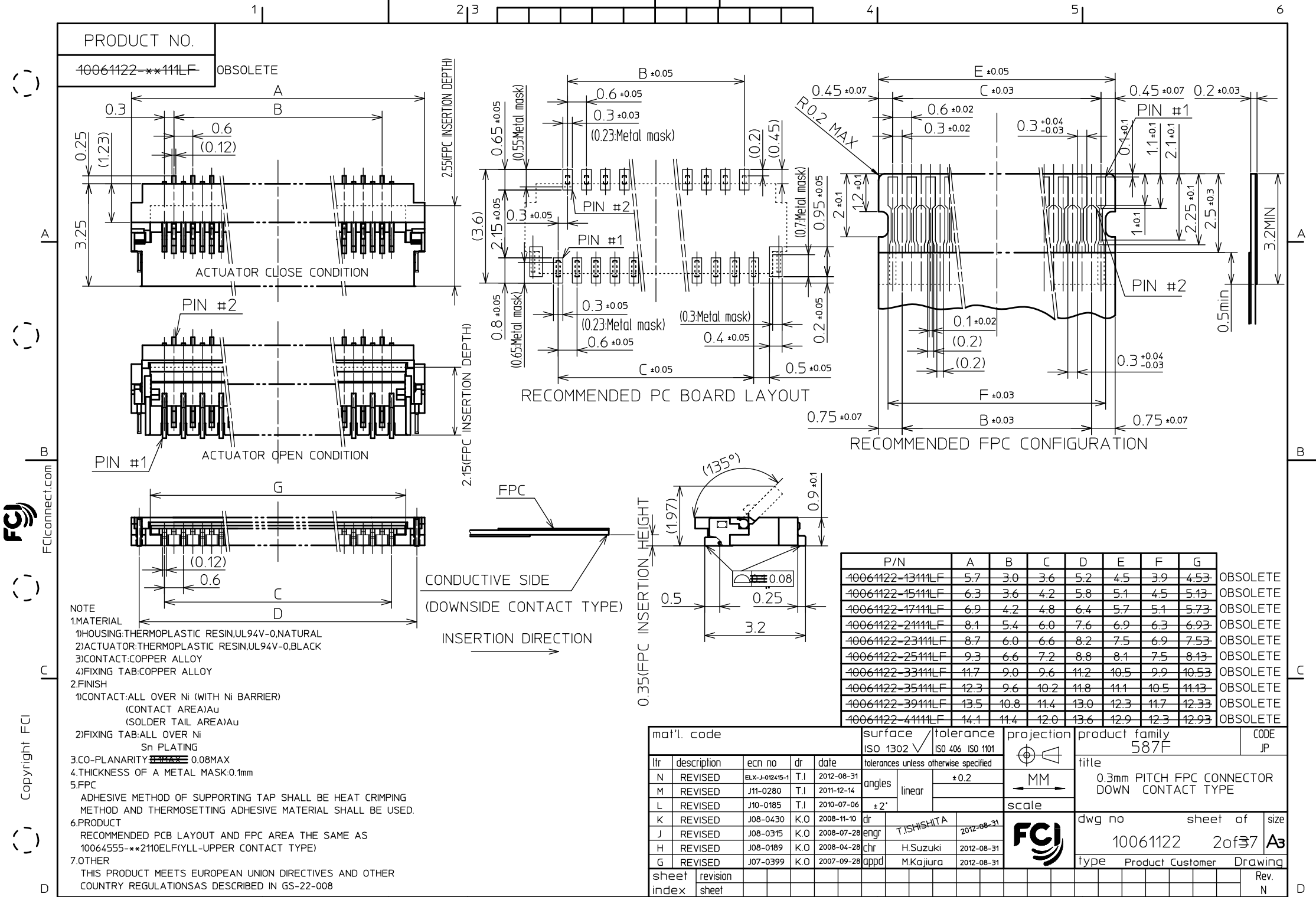
NO OF POSITION

SERIES NAME

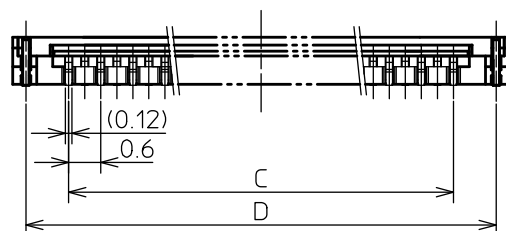
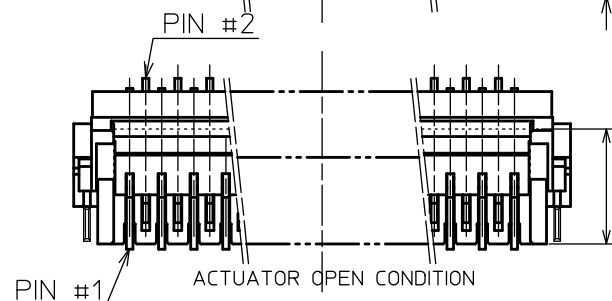
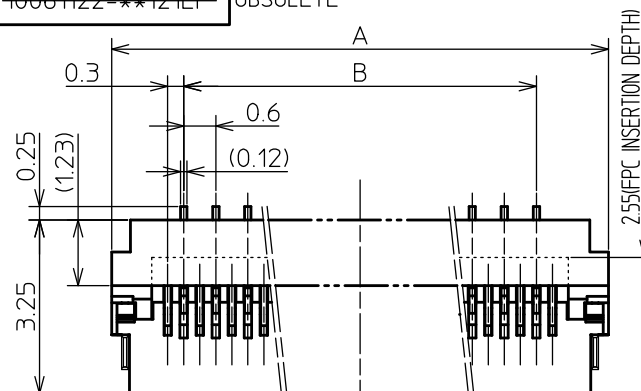


Actuator is close
Initial condition

mat'l. code					surface		tolerance		projection	product family 587F (YLL-D)	CODE JP
					ISO 1302		ISO 406 ISO 101				
l	tr	description	ecn no	dr	date	tolerances unless otherwise specified				title	
T	REVISED	ELX-J-20618	T.J		2015-04-17					0.3mm PITCH FPC CONNECTOR	
S	REVISED	ELX-J-14161	T.J		2013-03-05	angles linear ±0.3				DOWN CONTACT TYPE ET PACKAGING	
R	REVISED	ELX-J-0245	T.J		2012-08-31	±3			scale		
P	REVISED	J11-0280	T.J		2011-12-14					dwg no	sheet of size
N	REVISED	J10-0268	T.J		2010-10-12	engr	T.shishita	2015-04-17		10061122	10F37 A2
M	REVISED	J10-0185	T.J		2010-07-06	appr	M.Minato	2015-04-17			
L	REVISED	J10-0073	T.J		2010-05-17		N.Sasame	2015-04-17		type	Product Customer Drawing
sheet	revision	T	N	G	A	C	C	C			
index	sheet	1	2	3	4	5	6	7			Rev. I



OBSOLETE



NOTE

1.MATERIAL

- 1)HOUSING:THERMOPLASTIC RESIN,UL94V-0,NATURAL
2)ACTUATOR:THERMOPLASTIC RESIN,UL94V-0,BLACK
3)CONTACT:COPPER ALLOY
4)FIXING TAB:COPPER ALLOY

2 FINISH

- 1)CONTACT:ALL OVER Ni (WITH Ni BARRIER)
(CONTACT AREA)Au
(SOLDER TAIL AREA)Au
2)FIXING TAB:ALL OVER Ni
Sn PLATING

- 3.CO-PLANARITY:~~0.1MAX~~ 0.08MAX
4.THICKNESS OF A METAL MASK:0.1mm

5.FPC

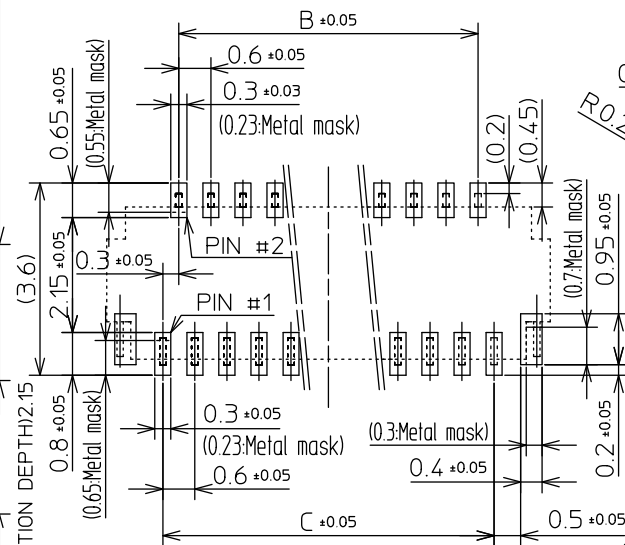
ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.

6 PRODUCT

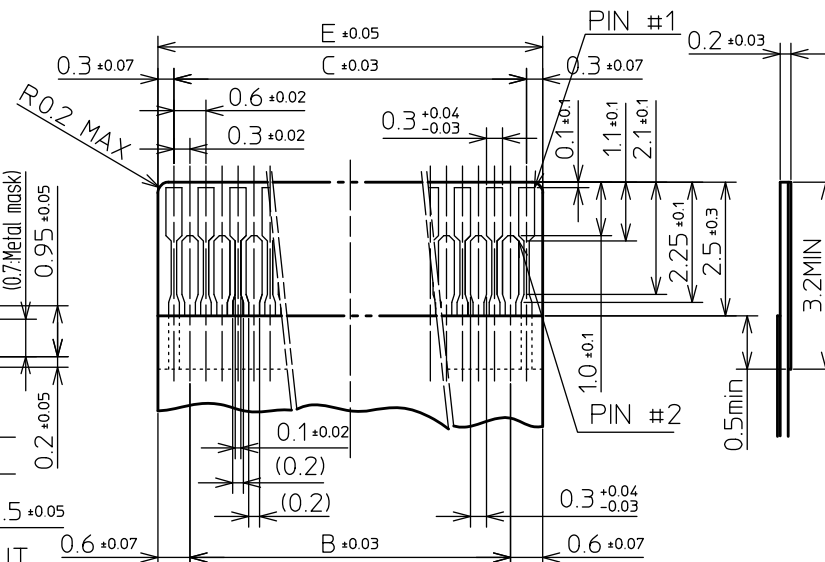
RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-**2210ELF(YLL-UPPER CONTACT TYPE)

7. OTHER

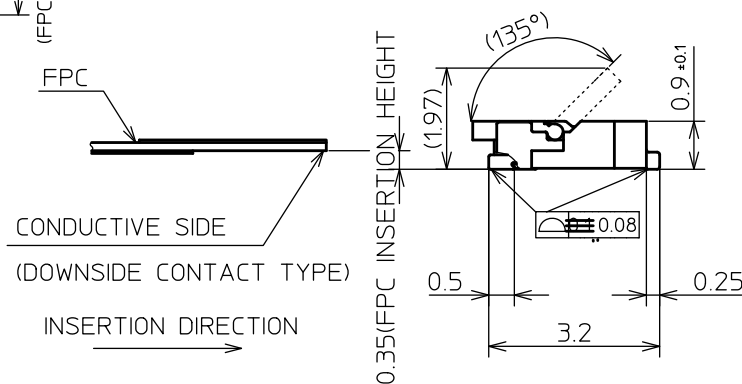
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008



RECOMMENDED PC BOARD LAYOUT

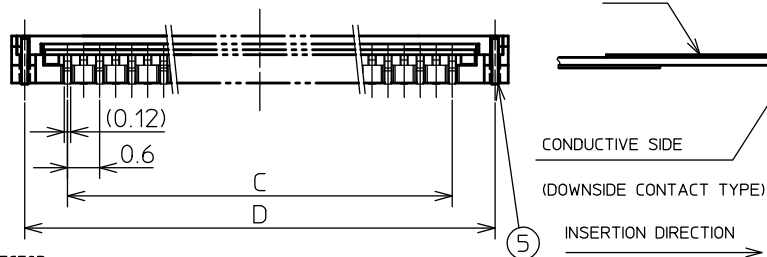


RECOMMENDED FPC CONFIGURATION



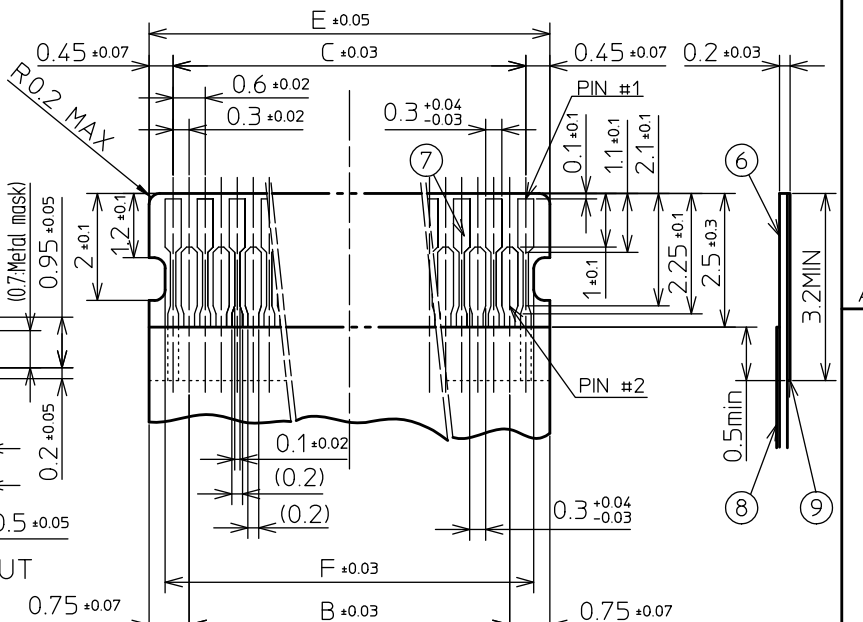
P/N	A	B	C	D	E	
40064122-45124LF	6.3	3.6	4.2	5.8	4.8	OBSOLETE
40064122-24124LF	8.1	5.4	6.0	7.6	6.6	OBSOLETE
40064122-23124LF	8.7	6.0	6.6	8.2	7.2	OBSOLETE
40064122-25124LF	9.3	6.6	7.2	8.8	7.8	OBSOLETE
40064122-33124LF	11.7	9.0	9.6	11.2	10.2	OBSOLETE
40064122-35124LF	12.3	9.6	10.2	11.8	10.8	OBSOLETE
40064122-37124LF	12.9	10.2	10.8	12.4	11.4	OBSOLETE
40064122-39124LF	13.5	10.8	11.4	13.0	12.0	OBSOLETE
40064122-44124LF	14.1	11.4	12.0	13.6	12.6	OBSOLETE
40064122-43124LF	14.7	12.0	12.6	14.2	13.2	OBSOLETE
40064122-45124LF	15.3	12.6	13.2	14.8	13.8	OBSOLETE

[illegible]



	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni WITH Ni BARRIER
4	CONTACT B	COPPER ALLOY	(n+1)/2	CONTACT AREA:Au SOLDER TAIL AREA:Au
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni Sn

This product meets European Union Directives and other country regulation as described in GS-22-008



RECOMMENDED FPC CONFIGURATION

NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

[illegible]

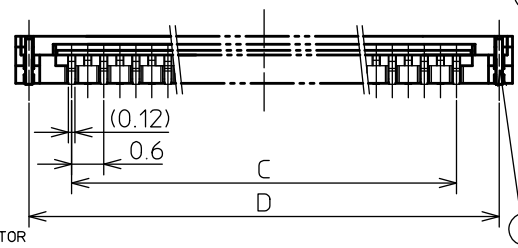
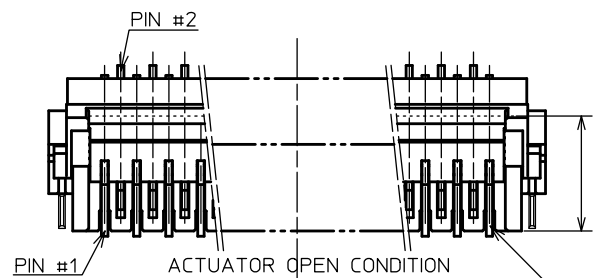
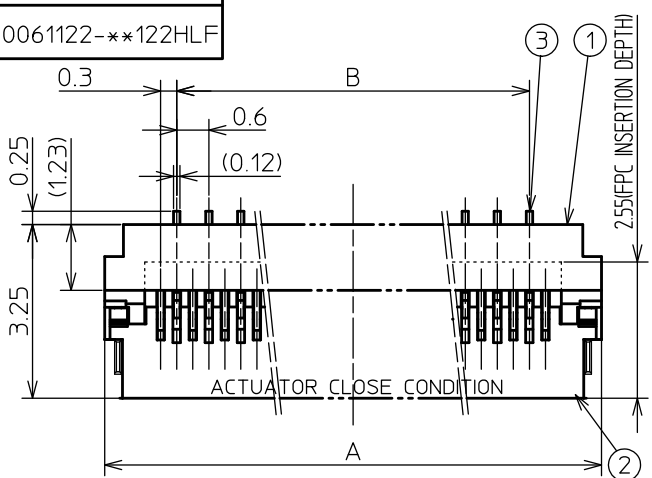


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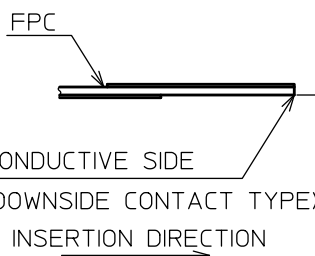
PRODUCT NO
10061122-**-122HLF



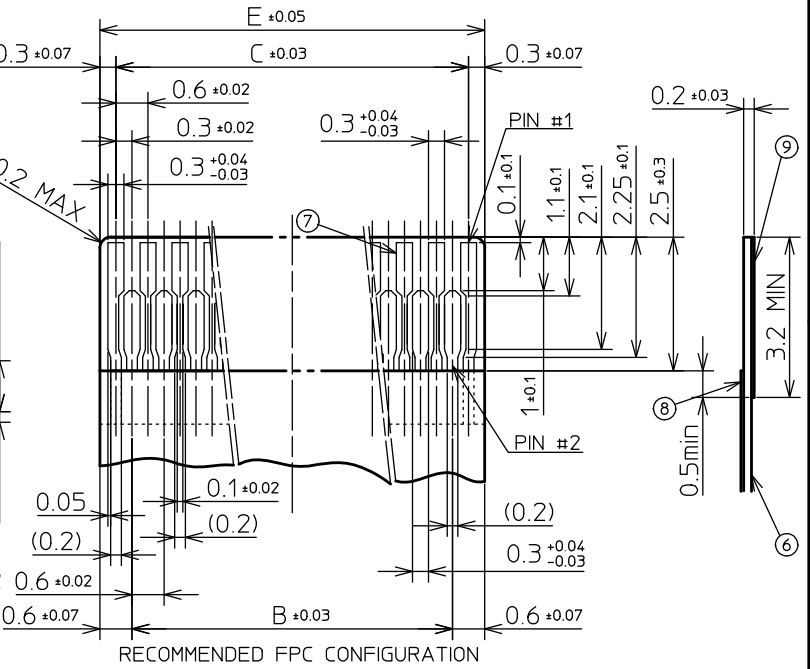
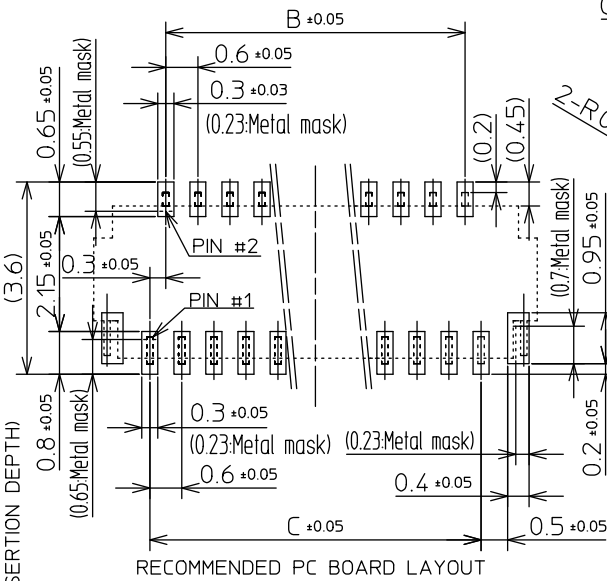
CONNECTOR

1	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:AU SOLDER TAIL AREA:AU
4	CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC
Adhesive method of supporting tape shall be heat crimping method
and thermosetting adhesive material shall be used.
4.PRODUCT
Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)
5.OTHER
This product meets European Union Directives and other country reguation
as described in GS-22-008



CONDUCTIVE SIDE
(DOWNSIDE CONTACT TYPE)
INSERTION DIRECTION

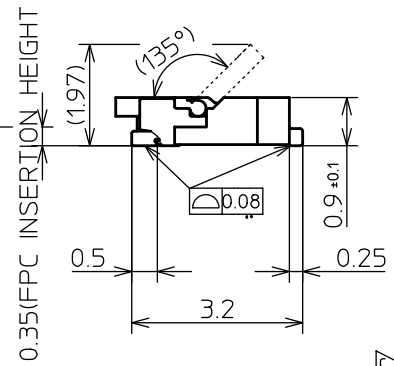


FPC	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

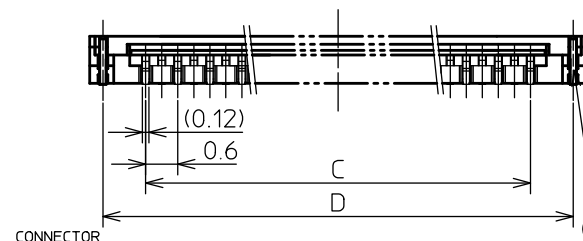
n:NO OF CONTACT

P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

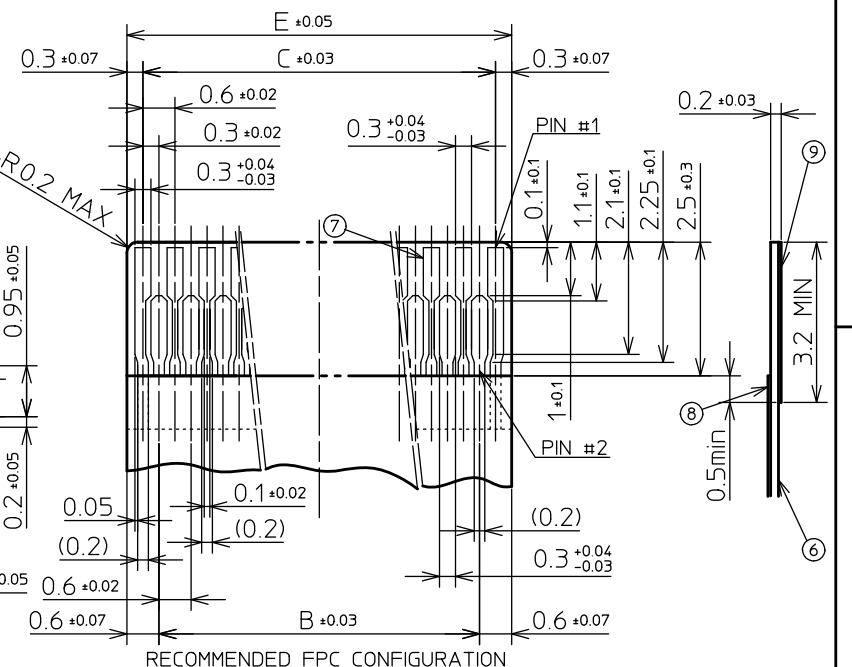
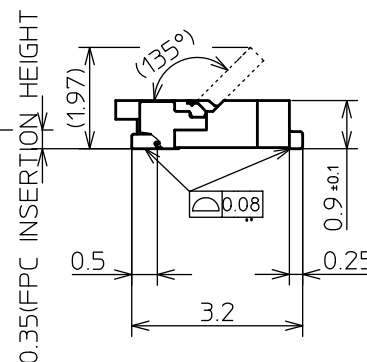
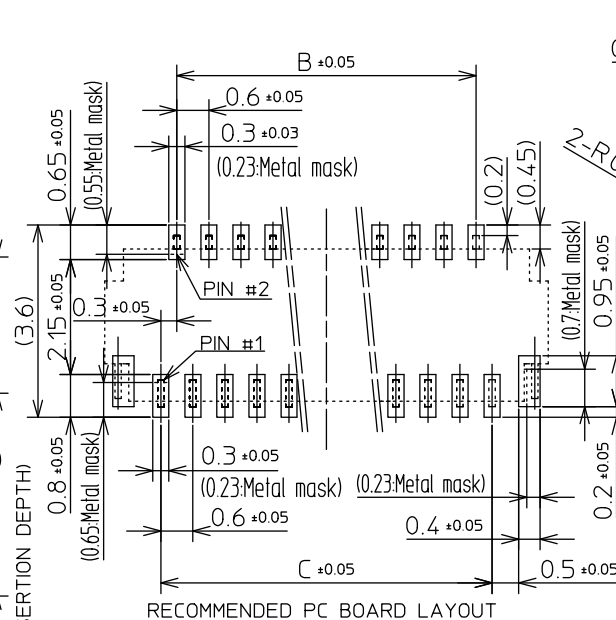
*For the corresponding position, please make an inquire to sales person in our company.



mat'l. code	surface	tolerance	projection	product family	CODE
ISO 1302	ISO 406	ISO 1101	MM	587F (YLL-D)	JP
lir	description	ecn no	dr	date	tolerances unless otherwise specified
A	Released	J10-0185	T.I	2010-07-06	± 0.2
B	Revised	ELX-J-12415	T.I	2012-08-31	linear
C	Revised	ELX-J-20618	T.I	2015-04-17	± 2'
dr	T.I	2015-04-17	engr	M.Minato	2015-04-17
chr	N.Sasame	2015-04-17	appd	N.Sasame	2015-04-17
sheet	revision	sheet	sheet	sheet	sheet
index	sheet	sheet	sheet	sheet	sheet



NOTE	nNO OF CONTACT
1.CO-PLANARITY:0.08mmMAX	
2.THICKNESS OF A METAL MASK:0.1mm	
3.FPC	
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.	
4.PRODUCT	
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)	
5.OTHER	
This product meets European Union Directives and other country regulation as described in GS-22-008	



FPC				
	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni $4-12 \mu m$ Au $0.05-0.15 \mu m$
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

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